

L Number	Hits	Search Text	DB	Time stamp
1	878	216/20.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 14:34
2	232	216/20.ccls. and polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 14:34
3	17	216/20.ccls. and polyimide near2 polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 14:36
4	81	216/20.ccls. and (polyimide with (etch\$4 or treat\$4 or rough\$5 or plasma or rie or (reactive adj ion)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 14:38
5	24	216/20.ccls. and (polyimide with (etch\$4 or treat\$4 or rough\$5 or plasma or rie or (reactive adj ion)) with adhes\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 14:39